

PMEG2010AEH; PMEG2010AET

1 A very low V_F MEGA Schottky barrier rectifiers

Rev. 03 — 28 March 2007

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifiers with an integrated guard ring for stress protection, encapsulated in small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
PMEG2010AEH	SOD123F	-	single
PMEG2010AET	SOT23	-	single

1.2 Features

- Forward current: $I_F \leq 1$ A
- Reverse voltage: $V_R \leq 20$ V
- Very low forward voltage
- Small SMD plastic packages

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

1.4 Quick reference data



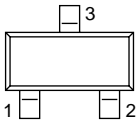
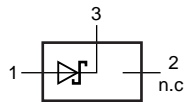
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55$ °C	-	-	1	A
V_R	reverse voltage		-	-	20	V
V_F	forward voltage	$I_F = 1$ A	[1] -	380	430	mV

[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
SOD123F			
1	cathode	[1]	 sym001
2	anode		
SOT23			
1	anode		 006aaa436
2	not connected		
3	cathode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2010AEH	-	plastic surface-mounted package; 2 leads	SOD123F
PMEG2010AET	-	plastic surface-mounted package; 3 leads	SOT23

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
PMEG2010AEH	AF
PMEG2010AET	*AX

[1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit		
V_R	reverse voltage		-	20	V		
I_F	forward current	$T_{sp} \leq 55\text{ °C}$	-	1	A		
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms};$ $\delta \leq 0.25$					
			PMEG2010AEH	-	7	A	
			PMEG2010AET	-	6	A	
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8\text{ ms}$	-	9	A		
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$					
			PMEG2010AEH	[1]	-	375	mW
				[2]	-	830	mW
			PMEG2010AET	[1]	-	280	mW
				[2]	-	420	mW
T_j	junction temperature		-	150	°C		
T_{amb}	ambient temperature		-65	+150	°C		
T_{stg}	storage temperature		-65	+150	°C		

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit		
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]					
			PMEG2010AEH	[2]	-	-	330	K/W
				[3]	-	-	150	K/W
			PMEG2010AET	[2]	-	-	440	K/W
				[3]	-	-	300	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]					
			PMEG2010AEH	-	-	60	K/W	
			PMEG2010AET	-	-	120	K/W	

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[4] Soldering point of cathode tab.

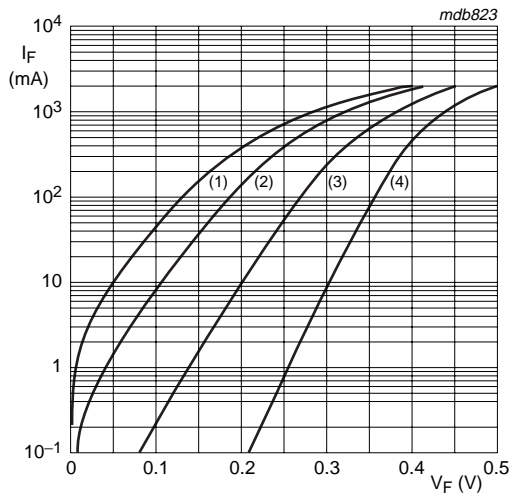
7. Characteristics

Table 8. Characteristics

$T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

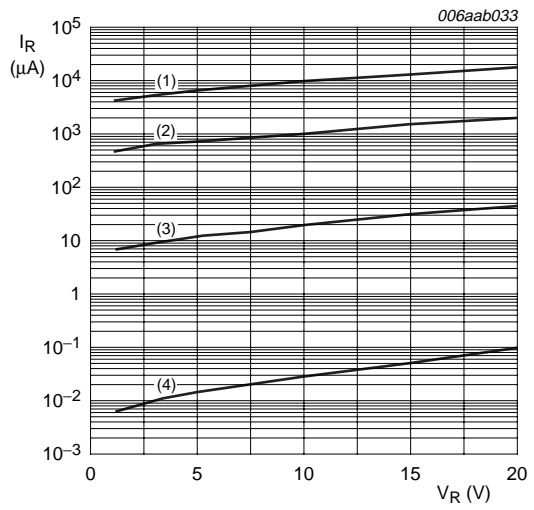
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 10\text{ mA}$	-	200	220	mV
		$I_F = 100\text{ mA}$	-	265	290	mV
		$I_F = 1\text{ A}$	-	380	430	mV
I_R	reverse current	$V_R = 5\text{ V}$	-	15	50	μA
		$V_R = 10\text{ V}$	-	20	80	μA
		$V_R = 20\text{ V}$	-	50	200	μA
C_d	diode capacitance	$V_R = 5\text{ V}; f = 1\text{ MHz}$	-	55	70	pF

[1] Pulse test: $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$.



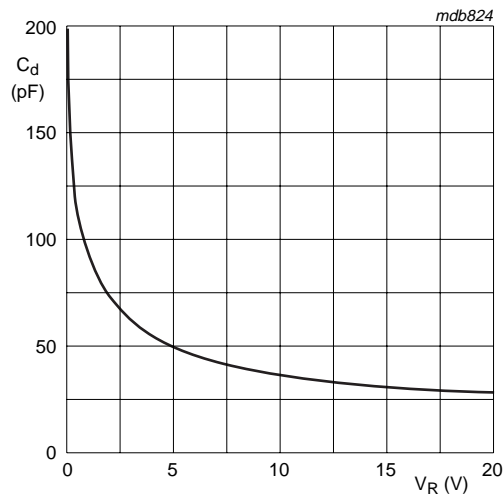
- (1) $T_{amb} = 125\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$
- (4) $T_{amb} = -40\text{ °C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 125\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$
- (4) $T_{amb} = -40\text{ °C}$

Fig 2. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information

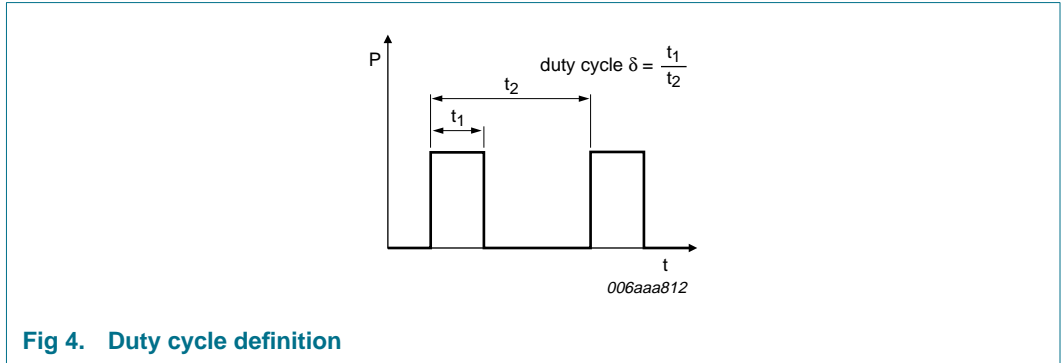


Fig 4. Duty cycle definition

9. Package outline

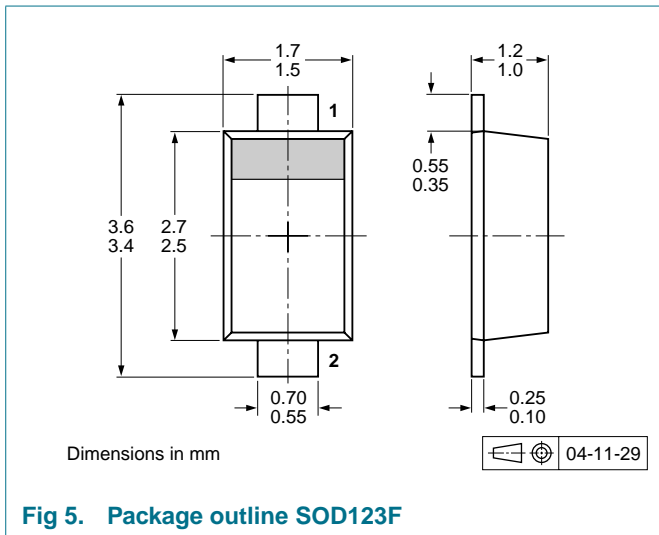


Fig 5. Package outline SOD123F

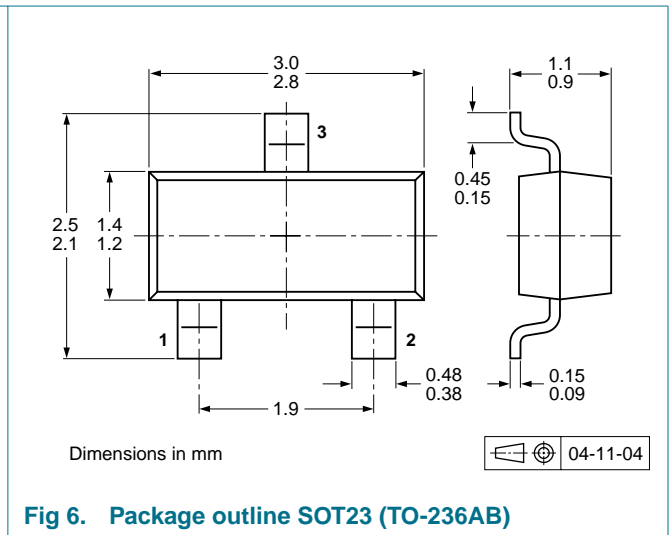


Fig 6. Package outline SOT23 (TO-236AB)

10. Packing information

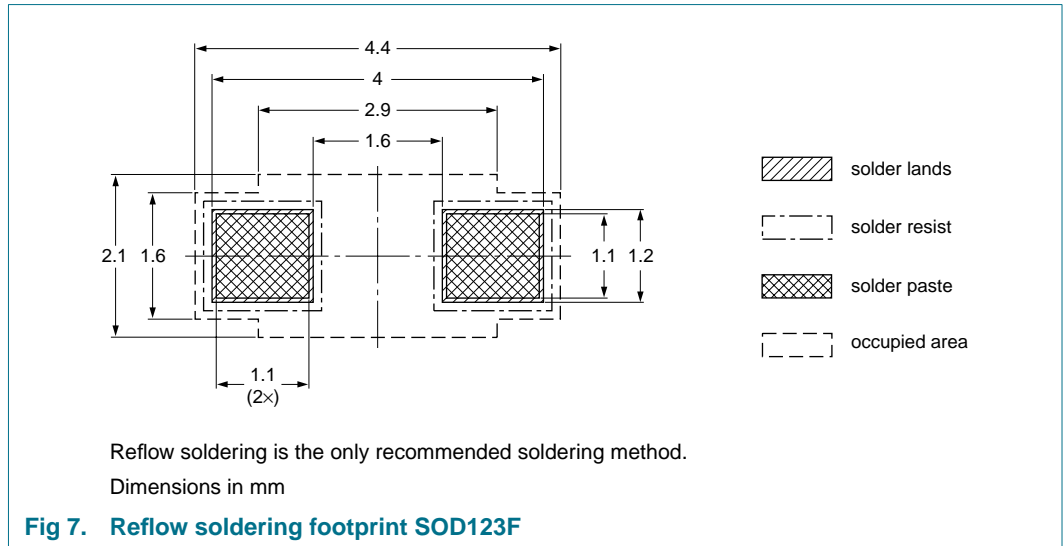
Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG2010AEH	SOD123F	4 mm pitch, 8 mm tape and reel	-115	-135
PMEG2010AET	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



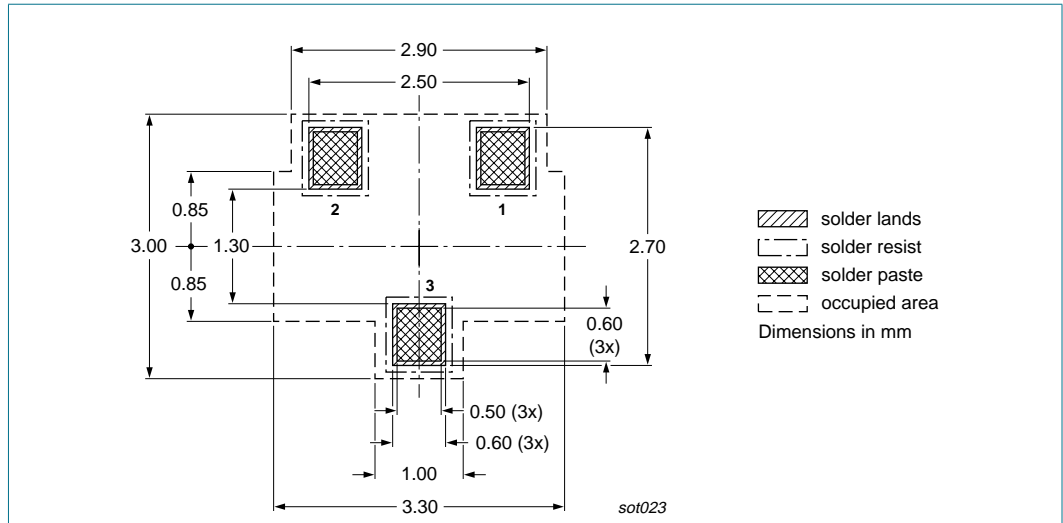


Fig 8. Reflow soldering footprint SOT23 (TO-236AB)

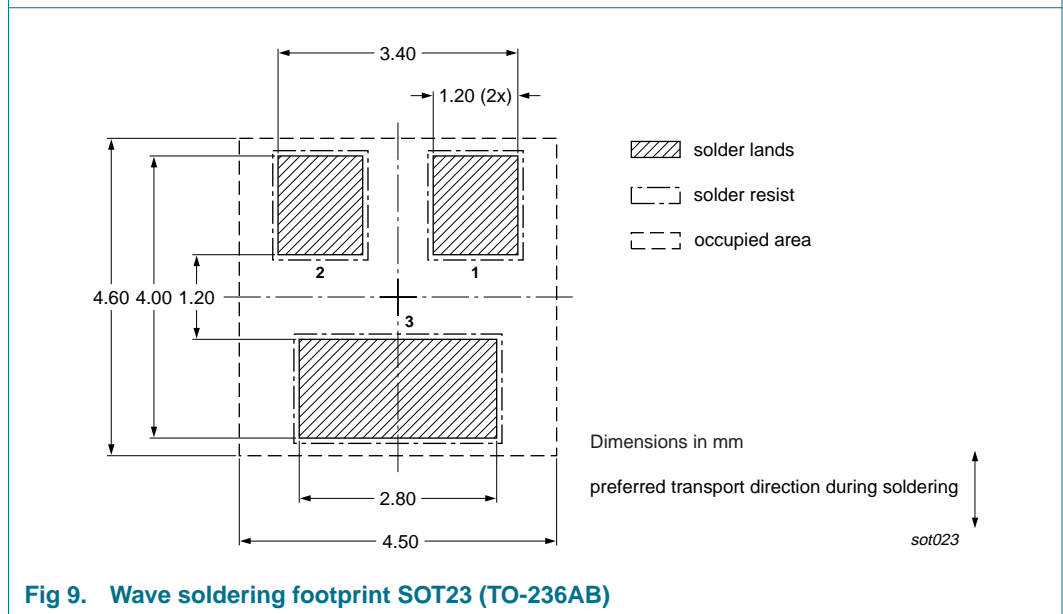


Fig 9. Wave soldering footprint SOT23 (TO-236AB)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2010AEH_PMEG2010AET_3	20070328	Product data sheet	-	PMEG2010AEH_2
Modifications: <ul style="list-style-type: none"> • The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number PMEG2010AET added • Section 1.1 "General description": amended • Table 1 "Product overview": added • Table 7 "Thermal characteristics": Table note 1 amended • Table 7 "Thermal characteristics": Table note 4 added • Table 8 "Characteristics": C_d diode capacitance conditions adapted • Figure 2: amended • Section 8 "Test information": added • Section 13 "Legal information": updated 				
PMEG2010AEH_2	20050526	Product data sheet	-	PMEG2010AEH_1
PMEG2010AEH_1	20050406	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

13.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

13.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or

malfunction of a NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

14. Contact information

For additional information, please visit: <http://www.nxp.com>

For sales office addresses, send an email to: salesaddresses@nxp.com

15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
5	Limiting values	3
6	Thermal characteristics	3
7	Characteristics	4
8	Test information	6
9	Package outline	6
10	Packing information	6
11	Soldering	7
12	Revision history	9
13	Legal information	10
13.1	Data sheet status	10
13.2	Definitions	10
13.3	Disclaimers	10
13.4	Trademarks	10
14	Contact information	10
15	Contents	11



Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2007.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 28 March 2007

Document identifier: PMEG2010AEH_PMEG2010AET_3



Поставка электронных компонентов

Юридический адрес организации:
198099, г. Санкт-Петербург, ул. Калинина, дом 2, кор. 4, лит А.
Фактический адрес организации:
198099, г. Санкт-Петербург, ул. Калинина, дом 2, кор. 4, лит А.
ИНН 780277764
КПП 780501001
Р/С 40702810422510004035 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в Санкт-Петербурге К/С 30101810900000000703
БИК 044030703
Телефон: 8 (812) 309-44-11 (многоканальный)
Факс: 8 (812) 309-44-11
Электронная почта: sales@timechips.ru
Сайт: timechips.ru

Информационное письмо

Компания «ТаймЧипс» - одна из наиболее динамично развивающихся компаний в сфере поставок электронных компонентов. Мы поставляем широкую номенклатуру электронных компонентов отечественных и импортных производителей, как напрямую, так и с крупных мировых складов, позволяющих охватить выборочную номенклатуру более 300 брендов, а также специализируемся на поставках дисплеев и является официальным дистрибьютором компании Shenzhen Startek Electronic Technology Co, на территории Российской Федерации.

Наличие собственной логистики позволяет в кратчайшие сроки доставлять товар нашим клиентам. В нашей компании имеется Конструкторский отдел, где наши специалисты проводят технические консультации клиентов, квалифицированную поддержку и помощь российским разработчикам. Осуществляем Поставки импортной продукции под контролем ВП МО РФ, на предприятия Оборонно-промышленного комплекса России. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001-2011.

Благодаря нацеленности на результат, мы уверенно занимаем новые позиции на рынке, заинтересовывая Клиента не только актуальными ценами и гибким подходом, но и постоянным вниманием.

Миссия – обеспечение долгосрочного и взаимовыгодного партнерства с клиентами.

Наша цель – Обеспечение клиентам самого широкого ассортимента электронных компонентов и бесперебойности поставок.

Мы - это развитие! Мы задаем темп! Мы разные, но вместе! Мы работаем для вас!

Так же имеем прямые поставки от производителей:

TAI-SAW Пав-компоненты (www.taisaw.com)

TRANSCOM СВЧ-компоненты (www.transcominc.com.tw)

Mini Circuits ВЧ-СВЧ-компоненты (minicircuits.com)

SAMTEC- разъемы (www.samtec.com)

4Star Разъемы РЧ (Даташиты по продукции 4Star, которые Вы сможете загрузить по этой ссылке: <https://yadi.sk/i/tPjnmGGrpmbYj>)

ULNION Преобразователи напряжения (converterdc.com/)

Отличные рекомендации на рынке, уверенность в качестве поставляемой продукции делают нас надежными партнерами для наших клиентов.

«ТаймЧипс» - это:

- Гарантия качества поставляемой продукции;
- Широкий ассортимент;
- Минимальные сроки поставок;
- Техническая поддержка;
- Подбор комплектации;
- Индивидуальный подход;
- Гибкие цены.

Модули, микросхемы, пассивные компоненты, Xilinx (XC), Altera (EP,EPF, EPM) и силовая электроника – это наши ведущие позиции, на поставку которых мы гарантированно дадим Вам самые выгодные предложения!

В структуру компании так же входит конструкторский отдел, который помогает разработчикам и конструкторам в решении следующих задач:

- Оценка стоимости проекта по компонентам;
- Подбор оптимального решения при выборе компонента;
- Подбор аналогов;
- Техническая поддержка;
- Консультации у производителей;
- Поставка прототипов;

С Уважением, Чернов Павел.

Руководитель отдела продаж ООО "ТАЙМЧИПС"

Официальный дистрибьютор Shenzhen Startek Electronic Technology Co.,Ltd в России (USB Display Modules , LED Displays, Serial Modules).

<http://www.timechips.ru/>

<http://lcd-timechips.ru/>

Телефон: +7 (812) 309-44-11 доб. 141

Факс: +7 (812) 309-44-11 доб. 152

Моб. Тел. +7 (905) 232-40-65

Skype: time.chips5

Электронная почта: manager1@timechips.ru
